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ABSTRACT

A printed circuit board according to an embodiment includes a first insulating layer, a second insulating layer disposed on the first insulating layer and including a cavity; and a pad disposed on the first insulating layer and having an upper surface exposed through the cavity; wherein the cavity includes a first part including a first inner wall; and a second part including a second inner wall under the first part; and wherein an inclination angle of the first inner wall is different from an inclination angle of the second inner wall.

